



DOCUMENT TITLE:
MARKETING OUTLINE, 49L CHIP SCALE BGA (7X7) 0.8MM PITCH, 1.4 THICK, 2 LAYER

DOC ID # 21-0356 NEW REV: A

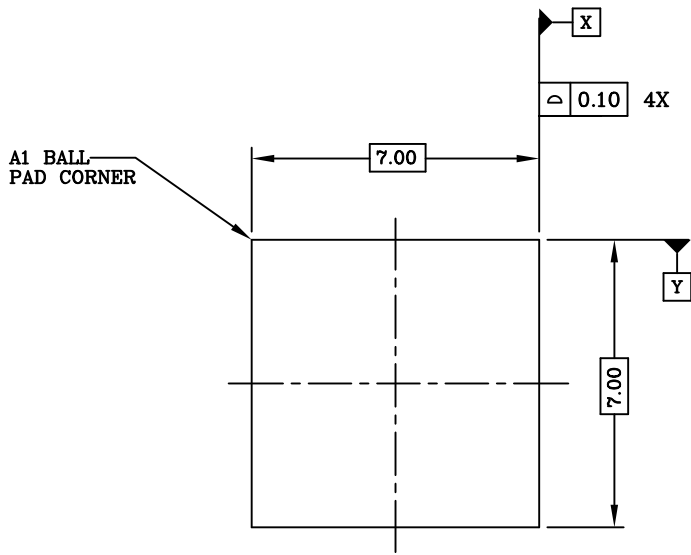
ECN#: HQ-08-5701 EFFECTIVE DATE: 07/15/08

ORIGINATOR: JEFF WALKER

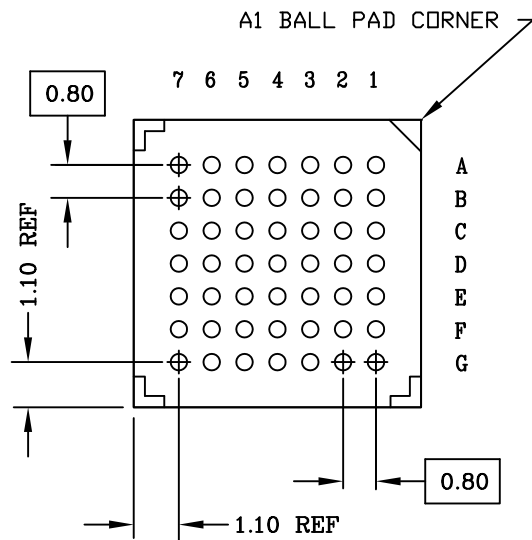
MOST RECENT CHANGES

FROM	TO
DALLAS DOCUMENT CONTROL SYSTEM DOC 56-G6006-001 LOGO-DALLAS/MAXIM	INITIAL RELEASE INTO MAXIM DOCUMENT CONTROL LOGO-MAXIM

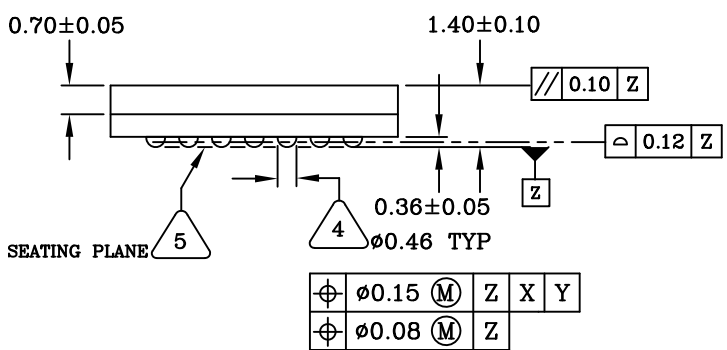
REVISIONS			
LTR.	DESCRIPTION	DATE	APPROVED
A			



TOP VIEW



BOTTOM VIEW



SIDE VIEW

NOTES:

- ⑤ PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- ④ DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.
- 3. THE BASIC SOLDER BUMP GRID PITCH IS 0.80
- 2. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994
- 1. DIMENSIONS ARE IN MILLIMETERS



SIGNATURE		DATE		MARKETING OUTLINE- 49L, CHIP SCALE BGA (7X7) 0.8 MM PITCH, 1.4MM THICK, 2 LAYER							
DDC. CONTROL:								SIZE	FSCM NO.	PART NO.	REV.
ENGR. MGR:								A		21-0356	A
MFG. ENGR:								SCALE	N/A	SHEET	1 of 1
CHECKED BY:											
DRAWN BY: NLK		3/00									
DO NOT SCALE DRAWING											

REVISION HISTORY

REV	CHANGES MADE	DATE	INIT.
A	ECN# HQ-08-5701. INITIAL RELEASE INTO MAXIM DOCUMENT CONTROL. LOGO-MAXIM	07/15/08	JW



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PAGE 3